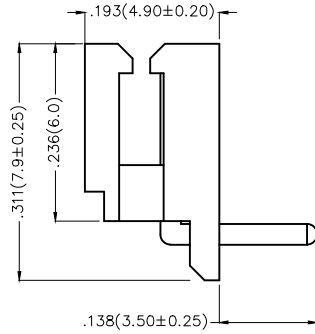
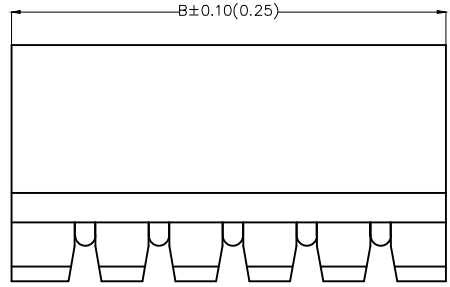
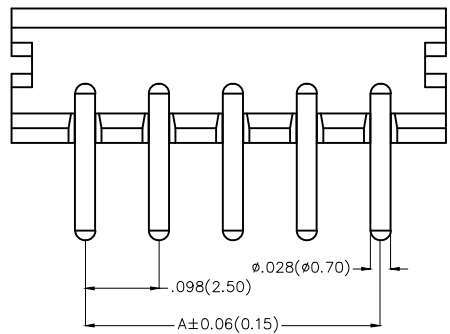


1	2	3	4	5	6	7	8
REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD		



Electrical
Current Rating: 3.0A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 20 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1000V AC r.m.s
Temperature Range—Operating: -25℃~+85℃
Material and Plating
Housing: PA66(UL 94V-0)
Contact Pin: Brass
Plating: Tin Plated

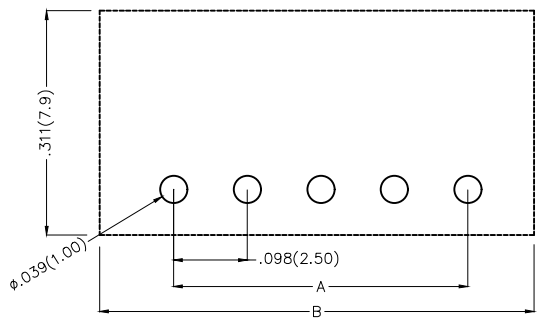


Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF25004-S02B22W5B	.098(2.50)	.295(7.50)
3	FWF25004-S03B22W5B	.197(5.00)	.394(10.00)
4	FWF25004-S04B22W5B	.295(7.50)	.492(12.50)
5	FWF25004-S05B22W5B	.394(10.00)	.591(15.00)
6	FWF25004-S06B22W5B	.492(12.50)	.689(17.50)
7	FWF25004-S07B22W5B	.591(15.00)	.787(20.00)

Ordering Information

FWF 250 04 — S XX B 2 2 W5 B
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 250—Pitch2.5mm	3	Distinction No. 04	4	Row Option Single Row	5	Circuits XX	6	Entry Angle B—90° Angle
7	Plating 2—Tin Plated	8	Material—Resin 2—PA66	9	Color—Resin W5—White	10	Packaging B—PE Bag				



Recommended P.C.Board Layout

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 01/JUL/13	PART NO. FWF25004-SXXB22W5B	ITEM NO. FWF25004	 TXGA Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE Wire to Board (Wafer) Pitch 2.5mm 90° Angled (DIP)	REV 0		
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X'±2°	JACOB	01/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		X.XX±.006(0.15)	.XX'±1°	DRAWN BY	DATE				
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX±0.5°	CHERRY	01/JUL/13				